



Avago Technologies To Present At Lehman Brothers High Yield Bond & Syndicated Loan Conference

March 21, 2007

SAN JOSE, Calif., – March 21, 2007 – Avago Technologies, a leading supplier of analog interface components for communications, industrial and consumer applications, today announced Avago management will participate in the Lehman Brothers High Yield Bond & Syndicated Loan Conference in Scottsdale, Ariz., on Tuesday, March 27 at 8:10 a.m. PT.

Event: Lehman Brothers High Yield Bond & Syndicated Loan Conference

Date: Tuesday, March 27, 2007

Time: 8:10 a.m. Pacific Time

Location: The Fairmont Scottsdale Princess

Webcast: www.avagotech.com/investor_comms/

About Avago Technologies

Avago Technologies is a leading supplier of analog interface components for communications, industrial and consumer applications. With a global employee presence, Avago provides an extensive range of analog, mixed-signal and optoelectronic components and subsystems to more than 40,000 customers. The Company's products serve four end markets: industrial and automotive, wired infrastructure, wireless communications, and computer peripherals. It is recognized for providing high-quality products along with strong customer service. Avago's heritage of technical innovation dates back 40 years to its Agilent/Hewlett-Packard roots. Information about Avago is available on the Web at www.avagotech.com.

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